INFORMATION DISCLOSURE CITATION (Use several sheets if necessary)			Docket Number (Optional)	Application Number
			SC12042ZK	Unknown
			Applicant(s)	
			Wang et al.	
•			Filing Date	Group Art Unit
			July 31, 2003	Unknown
*EXAMINER INITIAL		OTHER DOCUMENTS (Including Author, Title, Date, Pertinent Pages, Etc.)		
X.J.M.	1	John C. Carson, "Advances in Chip Level Packaging" (2002 Lecture notes, Johns Hopkins University)		
J.H. J.H. J.H.	2	"MicroPro Proves Effective for uBGA Sphere Attach", Speedline (a publication of Speedline Technologies), Issue #2 (Summer 2001)		
J.H.	3	D. Light, D. Castillo, M. Beroz, M. Nguyen, and T. Wang, "Vertical Expansion (WAVE) Packaging Process Development" (published by Tessera Technologies, 2001)		
J.H.	4	Joseph Fjelstad, "Strategies for Creating Compliant IC Packages at Near Chip Size" (INTERPACK 1999)		
J.J.L.	5	K. Klein, T. Leichle, E. Moss, P. Sassone and X. Wei, "A Survey of Compliant Interconnects for Wafer Level Packaging" (December 13, 2001)		
EXAMINER June 7 A. Musley DATE CONSIDERED 12/10/03				
EXAMINER: Initial if citation considered, whether or not citation is in conformance with MPEP Section 609; Draw line through citation if not in conformance and				

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not considered. Include copy of this form with next communication to applicant.